

June 2008

IEEE OTTAWA NEWSLETTER - June 2008

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News Submission: <http://ottawa.ieee.ca/news/submit.html>

IEEE Ottawa Section Website: <http://ottawa.ieee.ca/>

Newsletter on the Web: <http://ottawa.ieee.ca/news/>

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A. IEEE Ottawa Section Events

1. TITLE: Current Status and Future Trends for Si and Compound MMICs in Millimeter-wave Regime and Related Issues for System on Chip (SOC) and/or

System in Package (SIP) Applications

SPEAKER: Professor Huei Wang - IEEE MTT Distinguished Microwave Lecturer

National Taiwan University

DATE: June 23, 2008

TIME: 4:00-5:00pm

LOCATION: 4124 Mackenzie Engineering Building, Carleton University

PARKING: applicable charge

ADMISSION: free

REGISTRATION: n/a

ORGANIZED BY: Joint Seminar of the IEEE Ottawa AP/MTT, CPMT Chapters and

Department of Electronics, Carleton University

CONTACT: qiubo.ye@crc.ca

ABSTRACT: The anticipated presentation will cover the current status and

future trends of millimeter-wave MMICs, including those using III-V compound

(GaAs, InP, GaN, etc.) and Si-based (CMOS, SiGe HBT and BiCMOS) MMIC

technologies. Millimeter-wave MMICs used to be applied to military and astronomy systems for long time and started to be utilized for civil applications in the decade, such as communications and automotive radars. The

evolution of IC technologies has enabled the performance of Si-based MMICs

over 100 GHz, even in standard bulk CMOS processes. This is believed to have a

major impact in the future development of millimeter-wave systems. Since

low-cost mass-production potential pushes forward the technology, a very high

integration of circuit functions on a chip, such as RF, base-band circuitry, automatic-control for a steady operation, and maybe even the antenna, etc. should be included, and thus the system on chip (SOC) issues should be addressed, especially in MMW regime. Moreover, millimeter-wave packaging cost always dominated in the module development. In order to simplify the assembly and reduced cost, the concept of system in package (SIP) has been proposed. This presentation will also survey the current technologies for SOC and SIP and discuss related issues and challenges.

2. The IEEE Reliability Society in conjunction with its Ottawa Chapter, and the Student Branch coordinators will be hosting a series of presentations throughout a day this September.

Your action is needed:

- * If you wish more detail, or a reminder, as the planning is finalized, OR
- * If you wish to sponsor a presentation or the event, OR
- * If you wish to volunteer.

contact Raed Abdullah @ E-mail: RaedAbdullah@ieee.org

3. TITLE: ROSE 2008 - IEEE International Workshop on RObotic and Sensors Environments

SPEAKERS: on the website <http://www.site.uottawa.ca/ROSE2008/>

DATE: October 17 - 18, 2008

TIME: on the website <http://www.site.uottawa.ca/ROSE2008/>

LOCATION: SITE, University of Ottawa, Ottawa, Ontario, Canada

PARKING: on the website <http://www.site.uottawa.ca/ROSE2008/>

ADMISSION: on the website <http://www.site.uottawa.ca/ROSE2008/>

REGISTRATION: on the website

<http://www.site.uottawa.ca/ROSE2008/>
ORGANIZED BY: IEEE Canada, Vancouver Section and BC Hydro
TECHNICAL SPONSER: IEEE Ottawa Section
DETAILS: <http://www.site.uottawa.ca/ROSE2008/>
CONTACTS: Pierre Payeur (ppayeur@site.uottawa.ca),
Chris Dyer (cdyer@conferencecatalysts.com)
ABSTRACT: Not applicable/Not provided

B. IEEE News

1. New IEEE Senior Members in the Ottawa Section

The Following members were upgraded to Senior Member status in April 2008.

- * Aweya, James member of none of the Societies
- * Gillingham, Peter member of Solid-State Circuits Society

Congratulations for elevation to IEEE Senior member grade!

IEEE Senior Member Program Page:
<http://www.ieee.org/web/membership/senior-members/index.html>

2. TITLE:Electrical Power & Energy Conference (EPC 2008) "Energy Innovation"

SPEAKERS: on the website <http://www.ieee.ca/epc08>

DATE: October 6 - 7, 2008

TIME: on the website <http://www.ieee.ca/epc08>

LOCATION: Vancouver, British Columbia, Canada

PARKING: on the website <http://www.ieee.ca/epc08>

ADMISSION: on the website <http://www.ieee.ca/epc08>

REGISTRATION: on the website <http://www.ieee.ca/epc08>

ORGANIZED BY: IEEE Canada, Vancouver Section and BC Hydro

TECHNICAL SPONSER: IEEE Ottawa Section

DETAILS: <http://www.ieee.ca/epc08>

CONTACTS: Ebrahim Vaahedi and Moe Kia

ABSTRACT: Not applicable/Not provided

3. TITLE: 2008 IEEE International Carnahan Conference on Security Technology (ICCST), Prague, Czech Rep.
SPEAKERS: <http://www.ieee.org/iccst08>
DATE: October 13 - 16, 2008
TIME: <http://www.ieee.org/iccst08>
LOCATION: Diplomat Hotel Prague, Czech Republic
PARKING: <http://www.ieee.org/iccst08>
ADMISSION: <http://www.ieee.org/iccst08>
REGISTRATION: <http://www.ieee.org/iccst08>
ORGANIZED BY: IEEE Czechoslovakia Section & IEEE Aerospace and Electronic Systems Society
TECHNICAL SPONSER: IEEE Ottawa Section
DETAILS: <http://www.ieee.org/iccst08>
CONTACTS: Milo Klíma and Gordon Thomas
ABSTRACT: Not applicable/Not provided

4. Call for Fellow Nominations

Nominations are being accepted for the IEEE Fellows class of 2010.
The rank of

IEEE Fellow is the institute's highest member grade, bestowed on an IEEE

Senior Member who has had an extraordinary record of accomplishments in any of the IEEE fields of interest. The deadline for nominations is 1 March 2009.

Senior Members can be nominated in one of four categories: application engineer/ practitioner, research engineer/scientist, educator, or technical leader.

The Fellows Web pages contain information regarding the history of the IEEE

Fellows program, the nomination process, access to the Fellows Nomination Kit, lists of Fellows who are eligible to be references and more about the

Fellow

program. Please visit the Fellows website at <http://www.ieee.org/fellows>.

5. Clearing Up Confusion in Fellows Categories

*Originally published in The Institute and updated by Fellow Activities Staff *

Even though it's been nearly three years since nominations were first accepted for the newest Fellows category, Application Engineer/Practitioner, few have been nominated. Out of the 295 Fellows named in 2008, only 20 were from the practitioner group compared to the 15 in the 268 member Class of 2007. One reason might be because people are still unsure about the type of work that qualifies someone for this category, says 2003 IEEE President Michael Adler and chair of the IEEE Board-appointed 2008 Fellow Ad Hoc Committee, which reviews the Fellows process. Many nominators are checking off the Research Engineer/ Scientist box on the nomination forms when perhaps they should be marking the Application Engineer/Practitioner category, he says. The position of some nominees is identified to be that of a research scientist or engineer, but the work for which they are being cited could be considered that of a practitioner, Adler explains. There were 225 Fellows from the research engineer/scientist group in the 2008 class. To help clear up any confusion and help boost the number of Fellows from industry, here is a primer of the type of work that qualifies for the application engineer/practitioner category. The person has to be an IEEE senior member in good standing with five years of service in any grade of membership excluding affiliates, and who has

made significant contributions in any of these areas: product development, systems, applications or operations, project management or construction, process development, manufacturing innovations, or codes or standards development. Adler notes that it could be someone who develops a process to produce a product that may have been designed by others, and that has had a major impact. For example, among Fellows in the Application Engineer/Practitioner category, were those who invented and standardized elements of optical transmission systems, developed applications for satellite data and airborne LIDAR(light detection and ranging) imagery, researched signal processing for acoustics and sound reproduction, and provided technical leadership of a project that turned novel concepts for computer architecture into commercial processors. Nominations for the class of 2010 are now being accepted. The deadline is 1 March 2009. Nomination instructions, forms and additional information are available on the Fellows web site at <http://www.ieee.org/fellows>

C. Non-IEEE Events

1. TITLE : Short Course on Antenna Design, Testing & Wireless Propagation
SPEAKERS : Gilles Delisle, Daniel Janse van Rensburg & Derek McNamara
DATE : 2 - 5 June 2008
TIME : 08:30 - 16:30 Each Day
LOCATION : Campus of the University of Ottawa . Details of venue will be sent upon registration.

PARKING : Details will be sent upon registration.

ADMISSION : Please consult

<http://www.nearfield.com/ShortCourses.htm>

REGISTRATION : Please consult

<http://www.nearfield.com/ShortCourses.htm>

ORGANIZED BY: Electromagnetic Measurement Consultants

CONTACT: Derek McNamara, School of Information Technology & Engineering

(SITE),

University of Ottawa . Tel : +1 (613)562-5800 Ext.6221

E-Mail : mcnamara@site.uottawa.ca

ABSTRACT : This short course will provide an introduction to antenna concepts,

design and testing, as well as associated wireless propagation modeling. It is

intended for engineers and technicians who want to obtain a better understanding of antennas, and the physical concepts that describe their

operation and characteristics. The course will consist of lecture presentations on general concepts applicable to all antenna types, as well as

discussions on specific antennas in order to appreciate the application of such concepts.

2.

Tony Bailetti, host of TIM lecture series at Carleton University reported that

a conference titled "Blood on the tracks" was held on May 15. Initiatives that

came out of this conference are currently described on wiki and are accessible

via:

http://www.talentfirstnetwork.org/wiki/index.php?title=Blood_on_the_tracks:_6_years_of_technical_entrepreneurship_in_Ottawa

IEEE members are invited to contribute to these initiatives or propose better

ones. The greater the number and diversity of talented individuals with a common purpose, the better the outcomes of these initiatives will be.

We are welcoming good people to be part of this grass roots effort in support of technical entrepreneurship in Ottawa.

3. Google Job Posting:

Google is currently looking for EMC Design Engineers for the following job description below (EMC Society). relocation package is very competitive.

<http://www.google.com/support/jobs/bin/answer.py?answer=77628>

Contact Person: "Tod Vanlandingham" <todv@google.com>

EMC Design Engineer - Mountain View

This position is based in Mountain View, CA.

The area: Platforms

Google's global deployment of custom-designed machines has created one of the

largest and most powerful computing infrastructures in existence:

cutting-edge

innovation on a huge scale. The Platforms team designs and builds the software,

hardware, computing platform and networking technologies that power all of

Google's services. The role: EMC Design Engineer As an EMC

Engineer in

Platforms Engineering, you will play a key role in the development of

one of

the world's most impressive computing infrastructures! Your objective will be

to collaborate closely with our Hardware Design Teams to develop, test and

qualify products to be compliant with the relevant worldwide EMC standards and

regulatory requirements. This will involve engaging with various disciplines

(Electrical, Mechanical, Thermal, Power etc) as early as possible in the R&D

cycle to ensure compliance by design rather than retrofit at a later time. In addition you will be required to ensure all formal product certification documentation and labeling is in place for all deployment jurisdictions.

Responsibilities:

Work closely with hardware design teams and suppliers to understand new project architectures and requirements and subsequently provide design input, develop test plans and conduct compliance testing to extract key data to validate that all EMC goals are met in accordance with the relevant regulatory standards and specifications. Resolve complex non-compliant issues by the most efficient and cost effective methods. Ensure findings, risks and recommendations are clearly communicated to the various cross functional teams. Co-ordinate the process of formal certification and subsequently maintain high quality product technical files and reports. Cultivate good working relationships with customers, external suppliers, test labs and manufacturing partners.

Requirements:

Bachelor's degree in EE, or equivalent. M.S. or PhD in EMC or related discipline desirable. A minimum of 8 years hands-on EMC Design experience preferably with information Technology Equipment. Strong technical background and analytical knowledge of EMC and high speed design principles coupled with familiarity with a variety of software modeling tools. Good general understanding of hardware design constraints and tradeoffs and an ability to find cost effective work-arounds where feasible. Ability to simultaneously investigate multiple avenues to solve problems. Expert knowledge of international standards and procedures related to obtaining worldwide product certifications (e.g. FCC, CISPR, ICES, VCCI, etc.). Familiarity with test

equipment such as spectrum analyzers, oscilloscopes, LISN's, network analyzers, current probes, etc. Excellent understanding of product delivery lifecycles in a dynamic fast paced environment. Strong oral and written communication and interpersonal skills. Please contact: todv at google.com

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